PREFACE

Dear Distinguished Delegates and Guests,

International Conference on Electrical Information and Mechatronics (ICEIM2012) was held in Jiaozuo, China, from December 23-25, 2012, serving as a platform for expertise exchange. ICEIM 2012 had drawn the attention of researchers from various disciplines: Sustainable Electrical Information and Mechatronics, etc.
Persons who attended the conference were engineers, scientists, managers of various companies and professors of the universities abroad and home. We have had record number of submission 687 this year. From which 211 papers have been accepted for presentation at the conference and will be published by TTP, in Applied Mechanics and Materials (AMM) Journal (ISSN: 1660-9336), which is online available in full text via the platform www.scientific.net. AMM should be indexed by EI according the previous TTP index results.

We express our special gratitude to all the members of the General Committee Chairs, Program Committee Chairs, Technical Program Committee and Steering Committee who worked so hard to prepare the conference and who supported the conference so professionally.

International Conference on Electrical Information and Mechatronics (ICEIM2012)is organized by Henan Polytechnic University, co-organized by Chinese Academy of Sciences, Society of Intelligent Aerospace Systems (SIAS), Linear Motor Committees of China Electrotechnical Society, China, Zhejiang University, Southeast University, BeiHang University , Northwestern Polytechnical University, China University of Mining and Technology, Zhengzhou University and et al, and it sponsored by the fund from National Natural Science Foundation of China (NSFC). Their kind support makes ICEIM 2012 become possible. Especially, we should thank the TTP.

Finally, we would like to thanks all the authors, speakers and participants of this conference for taking part in and contributing to the International Conference on Electrical Information and Mechatronics.

We hope you have a unique, rewarding and enjoyable week at ICEIM2012 in Jiaozuo, China.

With our warmest regards,

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December 23-25, 2012
Jiaozuo, China

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